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RECORDATION FORM

Form PTO-1595 (Rev 01-09) OMB No 0651-0027 (exp 02/28/2009)

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To the Director of the U.S. Patent and Trademark Office. Please	record the attached documents or the new address(es) below
1. Name of conveying party(ies):	2. Name and address of receiving party(ies)
Akıhiro Yamada (12/18/2010), Atsuhıko Yamamoto (12/07/2010), and Hideo Kido	Name: Sony Corporation
(12/07/2010)	Internal Address
Additional name(s) of conveying party(ies) attached? Yes X No	Street Address:
3. Nature of conveyance/Execution Date(s): Execution Date(s)in parentheses after inventor name X Assignment Merger Change of Name Security Agreement Joint Research Agreement Government Interest Assignment Executive Order 9424, Confirmatory License	1-7-1 Konan Minato-Ku, Tokyo 108-0075 JAPAN City State Country Zip
Other	Additional name(s) & address(es) Yes X No attached?
A Patent Application No (s) This application Additional numbers attached 5. Name and address to whom correspondence concerning document should be mailed: Name Christopher M Tobin RADER, FISHMAN & GRAUER PLLC Internal Address Atty Dkt SON-4679 Street Address 1233 20th Street, N.W Suite 501	6. Total number of applications and patents involved: 7. Total fee (37 CFR 1.21(h) & 3 41) \$ 40 00
	None required (government interest not affecting titi
City Washington	8. Payment Information
State DC Zip 20036 Phone Number (202) 955-3750	•
(202) 055 3751	Deposit Account Number 18-0013
amt@raderfishman.com	Authorized User Name Christopher M Tobin
9 Signature) December 22, 2010
Signature	Total number of pages including cover 3
Christopher M. Tobin - 40,290	sheet, attachments, and documents
Name of Person Signing	

Attorney Docket No. 80001-4679 SONY Ref. No.: S11P0034US00

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in SOLID-STATE IMAGING APPARATUS, METHOD OF MANUFACTURING SAME, AND ELECTRONIC APPARATUS

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertunent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale

And I hereby authorize and request my attorney(s) of record in the spaces that follow. Scrial Number.	this application to insert the serial number and filing date of this application in, Filing Date:
This assignment executed on the dates indicated below.	
AKIHIRO YAMADA	
Name of first or sole inventor KANAGAWA JAPAN	Execution date of U.S. Patent Application
Residence of First or sole inventor	
Shippy hamide	Date of this assignment
Signature of first or sole inventor	Date of this assignment
ATSUHIKO YAMAMOTO	
Name of second inventor	Execution date of U.S. Patent Application
KANAGAWA JAPAN	
Residence of second inventor	
Signature of second inventor	Date of this assignment
HIDEO KIDO	ON O. D A lication
Name of third inventor	Execution date of U.S. Patent Application
KANAGAWA JAPAN	
Residence of third inventor	
Signature of third inventor	Date of this assignment

PATENT REEL: 025630 FRAME: 0437

Attorney Docket No. 80001-4679 SONY Ref. No.: \$11P0034L500

ASSIGNMENT

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for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address

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NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. I as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE its successors assigns, and legal representatives, the entire right title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property. Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto.

And I turther agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNLL or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense.

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he spaces that follow Serial Number.	this application to insert the serial number and filing date of this application is Filing Date:
his assignment executed on the dates indicated below	
AKIHIRO YAMADA	
Name of first or sole inventor KANAGAWA JAPAN	Execution date of U.S. Patent Application
Residence of First or sole inventor	
Signature of first or sole inventor	Date of this assignment
ATSUHIKO YAMAMOTO	
Name of second inventor KANAGAWA JAPAN	Execution date of U.S. Patent Application
Residence of second inventor Atsuble Vamanoto Signature of second inventor	December 7, 20/0 Date of this assignment
HIDEO KIDO	
Name of third inventor KANAGAWA JAPAN	Execution date of U S. Patent Application
Residence of third inventor Hiden Kido Bignature of third inventor	December 7, 20/0 Date of this assignment

PATENT REEL: 025630 FRAME: 0438